# MATERIAL DECLARATION DATA SHEET

| Device Name | Package Type | Pkg Wt (g) |
|---|---|---|
| A40MX02 | PLG44 | 2.400 |

| Material Breakdown of Component | Material Breakdown (%) | Substance Name | CAS No. | Weight (g) | Substance Mass (%) |
|---|---|---|---|---|---|
| MOLD COMPOUND | 78.88 | Silica | 60676-86-0 | 1.65644 | 87.5 |
| | | Resin | Proprietary | 0.17416 | 9.2 |
| | | Epoxy Cresol Novolac | 29690-82-2 | 0.05679 | 3 |
| | | Carbon Black | 1333-86-4 | 0.00568 | 0.3 |
| | | | | 1.89307 | 100 |
| LEADFRAME | 19.25 | Copper | 7440-50-8 | 0.45028 | 97.45 |
| | | Iron | 7439-89-6 | 0.01109 | 2.4 |
| | | Zinc | 7440-66-6 | 0.00055 | 0.12 |
| | | Phosphorus | 7723-14-0 | 0.00014 | 0.03 |
| | | | | 0.46206 | 100 |
| DIE | 0.75 | Silicon | 7440-21-3 | 0.01811 | 100 |
| | | | | 0.01811 | 100 |
| DIE ATTACH EPOXY | 0.14 | Silver | 7440-22-4 | 0.00229 | 70 |
| | | Epoxy Resin | Proprietary | 0.00098 | 30 |
| | | | | 0.00327 | 100 |
| BOND WIRE | 0.05 | Gold | 7440-57-5 | 0.00127 | 99.99 |
| | | Doping | Proprietary | 0.00000 | 0.01 |
| | | | | 0.00127 | 100 |
| EXTERNAL PLATING | 0.93 | Tin | 7440-31-5 | 0.02221 | 100 |
| | | | | 0.02221 | 100 |
| | | | | 2.400 | |

**Note: Microsemi believes this information to be correct, but cannot guarantee its completenes or accuracy as it is based on data received from sources outside our company.**

| Revision No. | Date | Description of Change |
|---|---|---|
| 0 | 5/13/2011 | Initial release |
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